

# SAC305水洗型锡膏

Sn96.5Ag3Cu0.5 Water Soluble Solder Paste

## FWS305

FWS-305 系列产品，是福英达自主研发与生产无卤水洗型的印刷锡膏，可减少焊料缺陷提高良率，提高焊点的可靠性，适用于系统级封装中的微组装焊接等领域。

FWS-305 series products are independently developed and produced by Fitech non-halogen water cleaning type of printed solder paste, which can reduce solder defects and increase yield, and improve solder joint reliability. Suitable for micro-assembly welding and other fields in SIP.

### 特性 Features



水洗环保型, 可靠性高

Good cleaning properties, High reliability



无卤素、无残留、无飞溅

Halogen-free, no residue, no solder splashing



采用优良的超微焊粉能在小间距及微组装上有良好的印刷性能

Using fine ultrafine powder, good printability in narrow pitch and micro assembly



提供低alpha值Sn96.5Ag3Cu0.5合金T6至T9的产品

Available in low alpha count Sn96.5Ag3Cu0.5 alloy Type6 to T9 products



触变性好, 粘度合适, 良好的润湿性与焊接性能

Good thixotropy, suitable viscosity, good wettability and solderability

### 印刷不同时间的印刷性能 Printing performance of different time



# SAC305水洗型锡膏 Sn96.5Ag3Cu0.5 Water Soluble Solder Paste

## 性能参数 Parameter

产品名称 Product	FWS-3055	FWS-3056	FWS-3057	FWS-3058	FWS-3059
锡粉尺寸 Size	T5 15-25 $\mu$ m	T6 5-15 $\mu$ m	T7 2-11 $\mu$ m	T8 2-8 $\mu$ m	T9 1-5 $\mu$ m
D50	20 $\mu$ m	9.5 $\mu$ m	6.0 $\mu$ m	5.3 $\mu$ m	3.3 $\mu$ m
涂覆方法 Using method	印刷 / printing	印刷 / printing	印刷 / printing	印刷 / printing	印刷 / printing
合金组成 Alloy	Sn96.5Ag3Cu0.5	Sn96.5Ag3Cu0.5	Sn96.5Ag3Cu0.5	Sn96.5Ag3Cu0.5	Sn96.5Ag3Cu0.5
粘度 Pa.s	80~140	80~140	80~140	80~140	80~140
Ti值	0.5~0.7	0.5~0.7	0.5~0.7	0.5~0.7	0.5~0.7
合金比例 Alloy %	86~88%	86~88%	86~88%	86~88%	86~88%
助焊剂比例 Flux %	12~14%	12~14%	12~14%	12~14%	12~14%
SIR	Pass $\checkmark$	Pass $\checkmark$	Pass $\checkmark$	Pass $\checkmark$	Pass $\checkmark$
锡珠测试 Solder ball	OK $\checkmark$	OK $\checkmark$	OK $\checkmark$	OK $\checkmark$	OK $\checkmark$
卤素含量 Halogen content	零卤素 氟元素或溴元素小于50 ppm, 总量小于100 ppm Zero Halogen Cl or Br <50 ppm, total <100 ppm				

\* 可按客户需求进行其他合金组成、锡粉尺寸及锡膏粘度进行定制。 Can be customized for other alloy composition, powder size and paste viscosity.

## 产品应用

### Product Application

微电子与半导体封装焊接材料，如模组、元件焊接，倒装芯片焊接，SIP 系统封装，Mini / Micro LED 封装等领域。

Microelectronics and semiconductor packaging welding materials, such as module, component welding, flip chip welding, SIP, Mini / Micro LED packaging and other fields.

## 注意事项 Precautions

### 01 过回流焊 / Reflow soldering

回流峰值温度高于熔点 (217-219 $^{\circ}$ C) 的温度 25~45 $^{\circ}$ C  
25 $^{\circ}$ C(min) ~ 45 $^{\circ}$ C(max) above Melting Temperature.

< 200PPM

T5 在氮气回流中氧气  
Type 5 Reflow in N<sub>2</sub> with < 200ppm O<sub>2</sub>

< 100PPM

T6 在氮气回流中氧气  
Type 6~9 Reflow in N<sub>2</sub> with <100 ppm O<sub>2</sub>

### 02 水清洗 / Water cleaning

过回流后在电路基板上有助焊剂残留物留要清洗，建议回流后尽快用去离子水加热至最低温度 25~40 $^{\circ}$ C进行清洗。

After reflow, there is flux residue on the circuit board to be cleaned. It is recommended to use deionized water as soon as possible after reflow to heat to the lowest temperature of 25~40 $^{\circ}$ C for cleaning.

### 03 产品储存 / Product storage

冰箱储存温度在 0~10 $^{\circ}$ C的条件  
Store at 0~10 $^{\circ}$ C